

As the below-named inventor, I declare that:

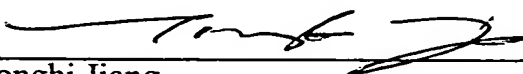
My residence, post office address, and citizenship are as stated below under my name.

I believe I am the original, first, and sole inventor of the invention entitled "METHOD OF PRESSURE CURING FOR REDUCING VOIDS IN A DIE ATTACH BONDLINE AND APPLICATIONS," which is described and claimed in the foregoing specification and for which a patent is sought.

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment specifically referred to herein (if any).

I acknowledge my duty to disclose information of which I am aware which is material to patentability and examination of this application in accordance with 37 C.F.R. § 1.56(a).

I further declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further, that these statements were made with the knowledge that the making of willfully false statements and the like is punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code, and may jeopardize the validity of any patent issuing from this patent application.



Tongbi Jiang

Date 1/28/00

Residence : City of Boise, County of Ada
State of Idaho
Citizenship : United States of America
P.O. Address : 12036 W. Patrina Drive
Boise, Idaho 83716

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicantd : Tongbi Jiang

Attorney Docket No.: 500180.01

Title : METHOD OF PRESSURE CURING FOR REDUCING VOIDS
IN A DIE ATTACH BONDLINE AND APPLICATIONS

Box Patent Application
Assistant Commissioner for Patents
Washington, DC 20231

ELECTION UNDER 37 C.F.R. §§ 3.71 AND 3.73 AND POWER OF ATTORNEY

Sir:

The undersigned, being Assignee of the entire interest in the above-identified application by virtue of an Assignment filed concurrently herewith, hereby elects, under 37 C.F.R. § 3.71, to prosecute the application to the exclusion of the inventors.

Assignee hereby appoints EDWARD W. BULCHIS, Reg. No. 26,847; JON F. TUTTLE, Reg. No. 25,713; PAUL T. MEIKLEJOHN, Reg. No. 26,569; GLENN P. RICKARDS, Reg. No. 29,428; DALE C. BARR, Reg. No. 40,498; KIMTON N. ENG, Reg. No. 43,605; DAVID E. BOONE, Reg. No. 27,857; SCOTT W. DOYLE, Reg. No. 39,176; REED R. HEIMBECHER, Reg. No. 36,353; JOHN T. KENNEDY, Reg. No. 42,717; GREGORY D. LEIBOLD, Reg. No. 36,408; GARY M. POLUMBUS, Reg. No. 25,364; THOMAS H. YOUNG, Reg. No. 25,796; W. ROBINSON H. CLARK, Reg. No. 41,530; GREGORY J. GLOVER, Reg. No. 34,173; JOHN K. HARROP, Reg. No. 41,817; CHRIS McWHINNEY, Reg. No. 42,875; ALDO NOTO, Reg. No. 35,628; MATTHEW PHILLIPS, Reg. No. 43,403; JOHN W. RYAN, Reg. No. 33,771; AMI P. SHAH, Reg. No. 42,143; SEAN S. WOODEN, Reg. No. 43,997; MICHAEL C. GILCHRIST, Reg. No. 40,619; BRIAN J. LAURENZO, Reg. No. 34,207; SHANE COLEMAN, Reg. No. 44,623; RONALD J. BROWN, Reg. No. 29,016; DAVID E. BRUHN, Reg. No. 36,762; DAVID N. FRONEK, Reg. No. 25,678; JOSEPH F. HAAG, Reg. No. 42,612; STUART R. HEMPHILL, Reg. No. 28,084; GRANT A. JOHNSON, Reg. No. 42,696; KENNETH E. LEVITT, Reg. No. 39,747; NIALA A. MACLEOD, Reg. No. 41,963; SCOTT A. MARKS, Reg. No. 44,902; DEVAN V. PADMANABHAN, Reg.

No. 38,262; GERALD H. SULLIVAN, Reg. No. 36,311; BRIAN PARK, Reg. No. P-45,519; MARK W. ROBERTS, Reg. No. P-46,160; of the firm of DORSEY & WHITNEY LLP, along with MICHAEL L. LYNCH, Reg. No. 30,871; LIA M. PAPPAS, Reg. No. 34,095; WALTER D. FIELDS, Reg. No. 37,130; CHARLES B. BRANTLEY, II, Reg. No. 38,086; KEVIN D. MARTIN, Reg. No. 37,882; and DAVID J. PAUL, Reg. No. 34,692, of MICRON TECHNOLOGY, INC., 8000 South Federal Way, Boise, Idaho 83706-9632, as its attorneys to prosecute this application and transact all business in the Patent and Trademark Office connected therewith. Please direct all telephone calls to **Kimton N. Eng** at (206) 903-8800 and telecopies to (206) 903-8820.

Please direct all communications to:

Kimton N. Eng, Esq.
Dorsey & Whitney LLP
1420 Fifth Avenue, Suite 3400
Seattle, Washington 98101
(206) 903-8800

Pursuant to 37 C.F.R. § 3.73, the undersigned duly authorized designee of Assignee certifies that the evidentiary documents have been reviewed, specifically the Assignment to MICRON TECHNOLOGY, INC., filed concurrently herewith for recording, a copy of which is attached hereto, and certifies that to the best of my knowledge and belief, title remains in the name of the Assignee.

MICRON TECHNOLOGY, INC.
ASSIGNEE

Feb 1, 2000
DATE

Michael L. Lynch
Michael L. Lynch
Chief Patent Counsel

Enclosure:
Copy of Assignment

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)
Tongbi Jiang) Docket No. 500180.01
Filed: Concurrently herewith) Disclosure No. 98-1193
For: METHOD OF PRESSURE CURING)
FOR REDUCING VOIDS IN A DIE)
ATTACH BONDLINE AND)
APPLICATIONS)

ASSIGNMENT:

X Enclosed for recording
____ Previously recorded
Date: _____
Reel: _____

FOR GOOD AND VALUABLE CONSIDERATION, the receipt, sufficiency and adequacy of which are hereby acknowledged, the undersigned does hereby:

SELL, ASSIGN AND TRANSFER to Micron Technology, Inc. (the "Assignee"), a corporation of Delaware, having a place of business at 8000 South Federal Way, Boise, Idaho 83706-9632, the entire right, title and interest for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned concurrently herewith and is entitled "METHOD OF PRESSURE CURING FOR REDUCING VOIDS IN A DIE ATTACH BONDLINE AND APPLICATIONS"; such application and all divisional, continuing, substitute, renewal, reissue and all other applications for patent which have been or shall be filed in the United States and all foreign countries on any of such improvements; all original and reissued patents which have been or shall be issued in the United States and all foreign countries on such improvements; and specifically including the right to file foreign applications under the provisions of any convention or treaty and claim priority based on such application in the United States of America;

AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on such improvements to the Assignee;

WARRANT AND COVENANT that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to

